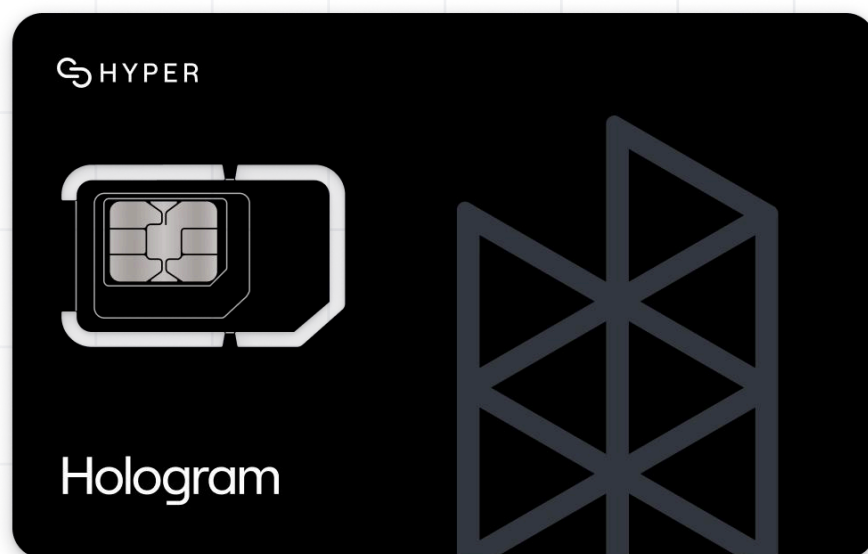


Triple cut format



Hyper eUICC SIM

Hyper eUICC SIM – Triple cut format

Product overview

A secure, device-agnostic IoT SGP.32 SIM card for global deployments built for M2M data, with easy activation, transparent pricing, and developer-friendly tools. Hologram's Hyper SIM platform is eUICC compliant and remotely updates coverage over-the-air by adding or removing connectivity profiles, without requiring you to swap the SIM in your device. Network fallback functionality can dynamically switch profiles in the event that a profile loses connectivity.

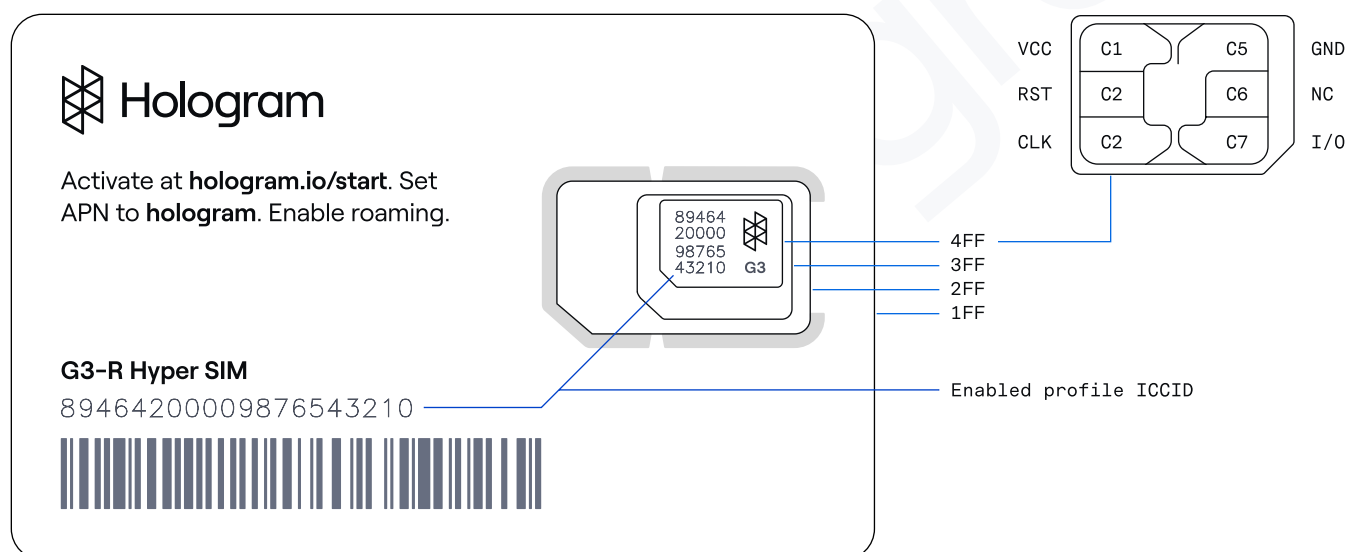
Primary part number

G3-R

Network availability

Works globally with Hologram's 2G through 5G network including LTE-M and NB-IoT where coverage is available. More information: <https://www.hologram.io/pricing/coverage>

Card layout



Physical characteristics

Size

1FF	Full-size	85.6 x 54 x 0.71 mm
2FF	Mini-SIM	25 x 15 x 0.71 mm
3FF	Micro-SIM	15 x 12 x 0.71 mm
4FF	Nano-SIM	12.3 x 8.8 x 0.71 mm

Pin definitions

C1	VCC	Input Voltage
C2	RST	Reset
C3	CLK	Clock
C5	GND	Ground
C6	NC	No Connect
C7	I/O	Input/Output

Hardware features

Chip type

Supplier	Infinion
Chip Code	SLM17ECB800B

Electrical

Operating Voltage	1.62V to 5.5V
-------------------	---------------

Hardware characteristics

Grade	Industrial
Operational Temperature	−40°C to +105°C
Data Retention	20 years @ 25°C
Write Endurance	>1.5M cycles
Memory (NVM)	800 KB
Memory (SRAM)	20 KB

AC electrical parameters standards

ETSI 3GPP TS 102 221 v16.0.0 - Smart Cards; UICC-Terminal interface; Physical and logical characteristics
ISO/IEC 7816, T=0 standard for Cards with contacts – USB electrical interface and operating procedures

Compliance

Chip



EAL 4+ PP-0084 (chipset)
Certificate: BSI-DSZ-CC-1126-V2-2021



SGP.22 RSP Technical Specification v2.5
SGP.32 eSIM IoT Technical Specifications v1.2

OS



eUICC Profile Package Interoperable Format Technical Specification v3.3.1



Card Specification Version 2.3.1
Card Specification Amendments A, B, D & E

Software



Java Card 3 Platform, Classic Edition version 3.0.5



Release 16

Remote SIM provisioning



SGP.22 RSP Technical Specification v2.5
SGP.32 eSIM IoT Technical Specifications v1.2

Supplier's Declaration of Conformity

Manufactured according to the following standards:

- RoHS 2015/863/EU
- Reach certification
- GSMA SAS-UP
- ISO 9001:2015
- ISO 27001
- ISO 14001

SIM features

Profiles and fallback

Available user memory	318,936 B
Maximum profiles	10
Applet version	v3 Recovery applet
Default fallback mode	Cyclical, 24 hour recovery

Part numbers

Active part numbers	Past part numbers
G3-R	—

Multipack labeling	Part numbers
Single SIM	G3-R
100-pack	G3-R-100
1000-pack	G3-R-1000